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## Optical Interconnects XIX

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## Contents

Vİİ	Authors Conference Committee
ix	Conterence Continuee
SESSION 1	ELECTRICAL-OPTICAL PCB TECHNOLOGIES
10924 02	Single-mode polymer waveguides and devices for high-speed on-board optical interconnect application (Invited Paper) [10924-1]
10924 03	Erbium-doped polymer waveguide amplifiers for PCB-integrated optical links [10924-3]
10924 04	Mode-mixing in multimode polymer waveguides for on-board optical interconnects [10924-4]
10924 05	Large-size directly inscribed polymer waveguide device for card-to-card optical interconnects application [10924-5]
SESSION 2	OPTICAL INTERCONNECT DEVICES AND MODULATORS
10924 07	Ultra-low power consumption silicon photonic link design analysis in the AIM PDK [10924-7]
SESSION 3	HYBRID INTEGRATED OPTICAL LINK MODULES
10924 0D	Through-substrate coupling elements for silicon-photonics-based short-reach optical interconnects (Invited Paper) [10924-13]
10924 OE	A new generation of high-speed electro-optical transceivers and flexible bandwidth wavelength selective switches for coherent DCI: the QAMeleon project approach (Invited Paper) [10924-14]
SESSION 4	OPTICAL INTERCONNECT SYSTEMS I
10924 OF	Fast optical switching technologies for inter/intra data center networks (Invited Paper) [10924-15]
10924 0H	Automated logic synthesis for electro-optic computing in integrated photonics [10924-17]
10924 OI	Modular test system for high-speed silicon photonics transceivers [10924-18]

SESSION 5	NOVEL OPTICAL WAVEGUIDE AND INTERCONNECT TECHNOLOGIES
10924 ON	SiN-assisted polymer-to-SiPh adiabatic coupler optimization [10924-22]
10924 00	Evaluation of the coupling performance and long-term stability of aerosol jet printed and photolithographic manufactured waveguides for asymmetric optical bus couplers [10924-23
SESSION 6	NANOPHOTONICS FOR OPTICAL INTERCONNECTS
10924 OR	Transfer of information using surface-plasmon-polariton waves [10924-26]
10924 OT	Dielectric metamaterial waveguide for optical interconnect and sensing (Invited Paper) [10924-28]
SESSION 7	FIBER OPTICS AND MICRO-OPTICS INTEGRATION
10924 OU	3D laser direct writing for advanced photonic integration (Invited Paper) [10924-29]
10924 OW	Fiber-coupled photonic interconnects based on stacked glass block connectors [10924-31]
10924 0X	Solder-reflowable single-mode fiber array photonics assembly in high-throughput manufacturing facilities (Invited Paper) [10924-32]
SESSION 8	PICS FOR OPTICAL INTERCONNECTS
10924 OZ	BaTiO <sub>3</sub> -based modulators for integrated optical interconnects (Invited Paper) [10924-34]
10924 10	MOICANA: monolithic cointegration of QD-based InP on SiN as a versatile platform for the demonstration of high-performance and low-cost PIC transmitters (Invited Paper) [10924-35]
10924 11	High-speed energy-efficient InP photonic integrated circuit transceivers (Invited Paper) [10924-36]
10924 12	Generation and recombination of free carriers in silicon nano-waveguides (Invited Paper) [10924-37]
SESSION 9	HYBRID DEVICE INTEGRATION APPROACHES FOR SILICON PHOTONIC CHIPS
10924 14	Unidirectional data center interconnects enabled by the use of broken-symmetry gap plasmon resonators (BS-GPR) [10924-39]

10924 15	Problems, challenges, and a critical survey on automated silicon photonics packaging and optical interconnection (Invited Paper) [10924-40]
10924 16	Backside optical I/O module for Si photonics integrated with electrical ICs using fan-out wafer-level packaging technology (Invited Paper) [10924-41]
10924 17	Polarization-insensitive glass-to-silicon photonics coupler [10924-42]
	POSTER SESSION
10924 1A	Wireless link evaluation of a dielectric resonator nanoantenna [10924-45]